

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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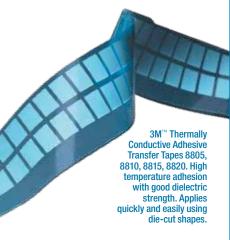


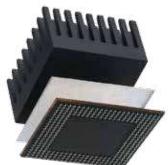






3M[™] Thermally Conductive Adhesive Transfer Tapes





Heat Sink.
Thermally Conductive
Adhesive Transfer Tape bonds
a heat sink to a component
and provides a thermal path
for component cooling.



This range of high adhesion thin tapes offers efficient thermal transfer for a wide range of applications requiring a thermal management solution: bonding heat sinks, heat spreaders and other cooling devices to IC packages, power transistors, and other heat generating components.

Each tape combines 3M high performance acrylic adhesive with highly conductive ceramic particles for an extremely reliable and user-friendly thermal interface. Highly conformable construction provides excellent wet-out on surfaces.

Select 5, 10, 15 and 20 mil thicknesses to meet application requirements.

3M™ Thermally Conductive Interface Materials Selection Guide

		Des	cription		Adhesion		ermal rmance	Diele Prope	ectric erties			
Product	Base Material Type	Product Thickness mil(mm)	Filler Type	Liner Type	Peel Strength @ 72 hr Dwell at RT (N/cm)	Conductivity (W/m-K)**	'C-in²/W (°C-cm²/W)	Dielectric Strength (kV/mm)	Volume Resistivity (ohm-cm)			
3M [™] Thermally Conductive Interface Tapes Softer - Improved Surface Conformability Acrylic Thermal Tape												
8805 8810 8815 8820	Filled Acrylic Polymer	5 (0.13) 10 (0.25) 15 (0.38) 20 (0.51)	Ceramic	Silicone Release Polyester Dual Liners	7.5 13.0 19.0 26.0	0.6	0.48 (3.1) 0.88 (5.7) 1.17 (7.6) 1.50 (9.7)	26 8815 tested	5.2 x 10 ¹¹ 3.9 x 10 ¹¹ 3.8 x 10 ¹¹ 3.8 x 10 ¹¹			
	3M™ Thermally Conductive Interface Tapes Standard Acrylic Thermal Tape											
9882 9885 9890	Filled Acrylic Polymer	2 (0.05) 5 (0.13) 10 (0.25)	Ceramic	Silicone Release Polyester	5 6.5 9.5	0.6	0.32 (2.1) 0.49 (3.2) 0.89 (5.7)	29 9890 tested	2 x 101 ⁴			
3M™ Theri High Adhes		ductive Inte	rface Ta	pes***								
TM-670SA* TM-671SA* TM-672SA*	Filled Acrylic	10 (0.25) 15 (0.375) 20 (0.5)	Ceramic	Silicone Release Polyester	25.0 /5.5 30.0/9.3 42.0/11.6	0.6	1.1 (7.1) 1.2 (7.8) 1.4 (9.1)	24 TM-670SA tested	-			
8943	Polymer	6.7 (0.17)		Film Liner	6.7	0.4	0.73 (4.7)	33 8940 tested				
		ductive Inte		pes								
8904-02		7.9 (0.2)			8.8	1.5	1.31 (8.49)	15	-			
8904-025	Filled	10 (0.25)		Clear PET Liner	11	1.5	1.35 (8.74)	15	-			
8904-05	Acrylic Polymer	20 (0.5)	Ceramic		9.9	1.5	1.50 (9.70)	15	-			
8940		7.5 (0.19)		Film Liner	6.7	0.4	0.78 (5.1)	33 8940 tested	_			
8910-03		11.8 (0.3)		Paper	20.5	0.6	1.1 (7.2)	23	-			

3M [™] Thermally Conductive Heat Spreading Tapes Thermally Conductive / Heat Spreading Tape											
9876-10	Acrylic Polymer	3.9 (0.1)	N/A	3M Logo Printed Silicone Release Paper	9	250 (X-Y)	0.21 (1.4)	20 9876-15	_		
9876-15	on Cu Laver	5.9 (0.15)		3M Logo Printed Film Liner	10	0.8 (Z-axis)	0.28 (1.8)	tested			

^{*} TM-67X tapes are designed with a high/low adhesion construction.
Face side or non-liner side when product roll is unwound is the lower adhesion side.

Note: The technical information and data on these pages should be considered representative or typical only and should not be used for specification purposes.

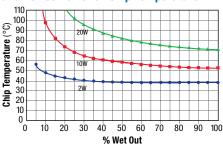
^{** 3}M tested in accordance with ASTM 05470TM method.

^{***} Products are special order in the USA. Please contact your 3M sales support for details.

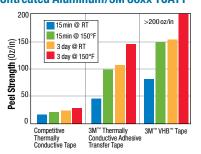
Effect of Thermal Interface Impedance and Device Power on Chip Temperature

110 100 90 80 70 60 Chip Temperature (°C) 20W 10W 50 40 30 20 2W 10 n 0.25 0.5 0.75 1.25 1.75 0 Impedance (C-in²/W)

Effect of Wet-Out (Interface Contact) and Device Power on Chip Temperature



90° Peel Adhesion to Bare **Untreated Aluminum/3M 88xx TCATT**



3M™ Thermally Conductive Interface Materials Selection Guide (Continued)

Product	UL Flammability Rating	Potential Operating Temperature Range* (°C)	Typical Applications	Notes		
3M™ Therma	Ily Conductive Interface Tape – Softer - Improv	ved Surface Conformability Acry	ylic Thermal Tape			
8805	UL Testing Note: Adhesive tapes are not	Short Term	Thermally conductive adhesive transfer tapes with high			
8810	intended to be used independently as a single component. Tapes are recognized for use with	(Hours-Days) 125-150	mechanical strength, improved surface wet-out, and excellent shock performance. Applications include:			
8815	specific substrates and the tape/substrate is tested for a UL rating.	Long Term (Weeks-Months) 90-100	heat sink attachment, flex circuit bonding, power device attachment and general thermal attachment solutions.			
8820	<u> </u>		actualisment and gonoral mornial actualisment conduction.			
	ally Conductive Interface Tape – Standard Acr	ylic Thermal Tape				
9882	UL Testing Note: Adhesive tapes are not intended to be used independently as a single	Short Term (Hours-Days) 125-150	3M's original thermally conductive adhesive transfer tape			
9885	component. Tapes are recognized for use with specific substrates and the tape/substrate is	Long Term	for applications requiring thin bonding with good thermal transfer.			
9890	tested for a UL rating.	(Weeks-Months) 90-100				
3M™ Therma	Ily Conductive Interface Tape – High Adhesion	**				
TM-670SA*		Short Term	3M TCAT TM-67X tapes are designed with a high/low			
TM-671SA*	Not Applicable - Non-Compliant	(Hours-Days) 110-130 Long Term	adhesion construction. Face side or non-liner side when product is unwound is the lower adhesion side for good			
TM-672SA*		(Weeks-Months) 80-90	reworkability.			
00.40		Short Term (Hours-Days) 125-150	Thermally conductive tape with good bonding strength.			
8943	Not Applicable	Long Term (Weeks-Months) 90-100	3M tape 8943 is a single coated tape version of 3M tape 8940.			
3M™ Therma	ally Conductive Adhesive Tapes (TCAT) – Flam	e Retardant Acrylic Thermal Ta	pe**			
8904-02	UL 94-V-0	Short Term (Hours-Days)		ANSI/UL 94 small-scale test data does not pertain to building materials, furnishings and related contents.		
8904-025	UL 94-V-0	80-90 Long Term (Weeks-Months)	High thermal conductivity adhesive tape (15W/m-k), application in LED and heat sink bonding. Re-workability and with excellent conformability to surfaces.	ANSI/U 94 small-scale test data is intended solely for determining the flammability of plastic materials used in the components and parts of end-product devices		
8904-05	UL 94-V-0	70-80	and with excellent comormability to surfaces.	and appliances, where the acceptability of the combination is determined by UL.		
	UL 94 V-0	Short Term (Hours-Days)				
8940	See UL listing for specifics of UL test criteria. Product tested with a substrate.	125-150 Long Term (Weeks-Months)	Thermally conductive tape with good bonding strength and flame retardant performance.			
		90-100		***************************************		
		Short Term (Hours-Days)	For the advanced thermally conductive tape with super	ANSI/UL 94 small-scale test data does not pertain to building materials, furnishings and related contents. ANSI/UL 94 small-scale test data is intended solely		
8910-03	UL 94 V-2	110 - 130 Long Term (Weeks-Months)	adhesion and good flame retardant, 3M TCAT 8910-03 can be considered and recommended as one of high	for determining the flammability of plastic materials		
		80 - 90	performance thermal attachment solutions.	used in the components and parts of end-product devices and appliances, where the acceptability of the combination is determined by UL.		
3M™ Therma	lly Conductive Heat Spreading Tapes	<u> </u>	l	-		
	m,as are rear oproduing rapes	Short Term (Hours-Days)		TCoHST has adhesive on one side only. Product		
9876-10		110-130	Excellent heat spreading on plane direction and low heat conduction on depth direction with good electrical	is not used to hold an assembly together. TCoHST		
9876-15		Long Term (Weeks-Months) 80-90	insulation on surface. It is designed for thermal management by heat spreading.	use is primarily heat spreading in low profile applications when attached to or on a surface opposite a hot device.		

^{*} End use application testing will determine final temperature range based on final design and other environmental conditions. Suggested temperature range is based on a UL-746 Test Method or a 3M Test Method.

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Through innovative 3M technology, these soft and conformable pads provide high levels of conductivity for the more demanding applications in the electronics industry. The pads provide excellent handling and can be die cut to fit most applications. Available in silicone and non-silicone elastomers.

- Thermal conductivity: 1.0-4.9 W/m-k
- Available in silicone and acrylic elastomers

Polymeric Supporting Film (S Versions) Filled Thermally Conductive Silicone Elastomer Removable Release Liner

3M™ Thermally Conductive Interface Pads Selection Guide

	De	escription			Adhesion/Shore 00 Softness		ermal ormance		ectric erties							
Product	Base Material Type	Product Thick- ness mil (mm)	Filler Type	Liner Type	Adhesion Characterization/// Shore 00 Testing based on TM 6 mm thickness	Conductivity** (W/m-K)	Impedance*** °C-in²/W (°C-cm²/W)	Dielectric Strength kV/mm	Volume Resistivity (Ohm-cm)							
3M™ Thermally	Conduct	tive Silico	ne	Inte	rface Pads											
5514					No added adhesive layer. Pad is tacky and conformable/// Shore 00=58	1.6	0.44 (2.8) 0.47 (3.0)	14.0	8.6 × 10 ¹³							
5515	Filled Silico	7.9 (0.2) 9.8 (0.25)			No added adhesive layer.	3.0	0.29 (1.8) 0.40 (2.6)	14.5	3.6 × 10 ¹⁴							
5515S*					Pad is tacky and conformable/// Shore 00=80	2.7	0.62 (3.9) 0.70 (4.5)	17.7	8.6 × 10 ¹⁴							
5516									20 (0.5)			No added adhesive laver.		0.31 (2.0)	13.1	
5516S*		40 (1.0) 60 (1.5) 80 (2.0)			Pad is tacky and conformable/// Shore 00=50	3.1	0.53 (3.4) 0.75 (4.9) 0.98 (6.3)	16.0	6.9 × 10 ¹⁴							
5517		40 (1.0) 60 (1.5) 80 (2.0) 20 (0.5) 40 (1.0) 60 (1.5) 80 (2.0)			No adhesive layer. Pad is tacky and highly conformable/// Shore = 33	3	0.73 (4.7) 0.98 (6.3) 1.22 (7.9)	4.1	5.0 × 10 ¹³							
5519			d Silico	Silico	20 (0.5) 40 (1.0)	Ceramic	PET	No added adhesive layer.		0.29 (1.9) 0.48 (3.1)	11.1					
5519S*	ne Polym	60 (1.5) 80 (2.0)	mic		Pad is tacky and conformable/// Shore 00=70	4.9	0.65 (4.2) 0.82 (5.3)	13.5	1.7 × 10 ¹⁴							
5591	9	20 (0.5) 40 (1.0)			No added adhesive layer.		1.14 (7.3) 1.92 (12.4)	5.5								
5591S*		60 (1.5) 80 (2.0)			Pad is tacky and conformable/// Shore 00=10-15	1.0	2.71 (17.5) 3.49 (22.5)	7.9	2.0 × 10 ¹²							
5592		20 (0.5) 40 (1.0)			No added adhesive layer.		0.64 (4.1) 1.15 (7.4)	12.2								
5592\$*		60 (1.5) 80 (2.0)			Pad is tacky and conformable/// Shore 00=43	1.1	1.66 (10.7) 2.43 (15.7)	14.7	3.0 × 10 ¹²							
5595			20 (0.5) 40 (1.0)			No added adhesive layer. Pad is tacky and conformable///	1.6	0.70 (4,5) 1.21 (7.8)	13.1	E 0 1012						
5595\$*		60 (1.5) 80 (2.0)		Shore 00=50		1.0	1.71 (11.0) 2.22 (14.3)	15.7	5.0 × 10 ¹²							
3M™ Thermally	Conduct	tive Acryl	ic I	nter	face Pads											
							0.67 (4.3)									

3M Thermally	Conduct	LIVE ACI YI	IC II	ILGI	lace I aus				
5570		20 (0.5) 40 (1.0)		PET	No added adhesive layer. Pad is tacky and conformable/// Shore 00=50	1.3	0.67 (4.3) 1.18 (7.6) 1.69 (10.9) 2.30 (14.9)	20	2.9 × 10 ¹²
5571	필	60 (1.5) 80 (2.0)			No added adhesive layer. Pad is tacky and conformable/// Shore 00 = 70	2	0.81 (5.2) 1.24 (8.0) 1.68 (10.8) 2.11 (13.6)	23	3.3 × 10 ¹²
5578H	Filled Acrylic Polymer	20 (0.5) 40 (1.0)	Ceramic		No added adhesive layer. Pad is tacky and conformable/// Shore 00 = 70	3.5	0.81 (5.4)	19	1.7 × 10 ¹²
5589H	olymer	40 (1.0) 60 (1.5)	.,		No added adhesive layer. Pad is tacky and conformable/// Shore 00=48	2.0	1.33 (8.6) 1.67 (10.8)	21	3.4 × 10 ¹²
5590H	20 (0.5) 40 (1.0) 60 (1.5)				No added adhesive layer. Pad is tacky and conformable/// Shore 00=61	3.0	0.46 (3.0) 0.70 (4.5) 0.95 (6.1)	16	2.7 × 10 ¹²
5567H		20 (0.5) 40 (1.0) 60 (1.5)			No added adhesive layer. Pad is tacky and conformable/// Shore 00=63	3.0	0.46 (3.0) 0.70 (4.5) 0.95 (6.1)	16	2.7 × 10 ¹²

- *Pads ending with S have a polymeric film on one side to be used as a non-tacky surface for ease of reworking an assembly.
- **3M tested in accordance with ASTM 05470 test method.

 ***Thermal impedance is measured with the test sample under a nominal 10 psi pressure to reflect a typical end use application.

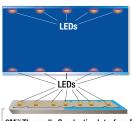
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LED BLU Application

LED Assembly



3M™ Thermally Conductive Interface Pads or 3M[™] Thermally Conductive Interface Tapes Heat Sink or Heat Spreader Plate

Automotive Battery Application

Battery Assembly

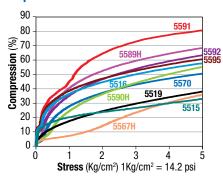


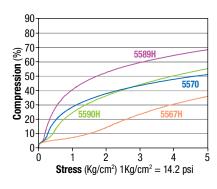
3M™ Thermally Conductive Acrylic Interface Pads

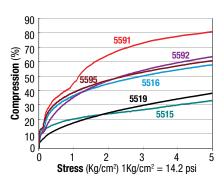
Notebook Thermal Module Application



Compression vs. Stress







3M™ Thermally Conductive Interface Pads Selection Guide (Continued)

Product	UL Flammability Rating	Potential Operating Temperature Range****(°C)	Typical Applications	Notes						
3M™ Thermally (Conductive Silicone	e Interface Pads								
5514	UL 94 V-1		3MPad5514 is designed for applications requiring complicated shape, thin thickness (<0.25 mm) and good flexibility with over-bending.							
5515	UL 94 V-0	Short Term (Hours-Days)	(Hours-Days)	(Hours-Days)					3M Pad 5515 is designed for applications requiring higher K(3 w/m-k) and thin thickness ($<\!0.25\text{mm}$).	Thermally conductive interface
5515S	Not Applicable				3M Pad 5515S is Thermal Pad 5515 with a permanent polyimide film on one side to be used as a non- tacky surface for anti-abrsion and ease of reworking on assembly. Thermal conductivity and thermal impedance are slightly changed with addition of thin polyimide film.	pads (silicone) for applications requiring gap filling and superior thermal performance without bonding. Provides IC package				
5516	UL 94 V-0	_ 180-200°C Long Term	 3M Pad 5516S is Thermal Pad 5516 with a polymeric permanent film on one side to be used as a non-tacky surface for ease of reworking an assembly. Thermal conductivity and thermal 	and PCB thermal interfacing						
5516S	UL 94 V-1 or V-0	(Weeks-Months) 150-160°C	impedance are slightly changed with addition of the film, while Dielectric strength is improved. 2) Optional thickness > 2.0 mm are available.	with heat sinks or other cooling device, and metal cases.						
5517	_	-	3M Pad 5517 is a highly conformable, slightly tacky silicone elastomer flexible to fit to the shape.	"S" designation signifies a polyester (PET) or a PEN film on						
5519		-	3M Pad 5519S is Thermal Pad 5519 with a polymeric permanent film on one side to be used as a non-tacky surface for ease of reworking an assembly. Thermal conductivity and thermal	one side to provide a non-tacky surface. "H" designation signifies a product with one non-tacky						
5519S	UL 94 V-0		impedance are slightly changed with addition of the film, while Dielectric strength is improved. 2) Optional thickness > 2.0 mm are available.	surface without the use of a PET film.						
5591	Not Applicable	 3M Pad 5591S has a polymeric permanent film on one side to be used as a non-tacky surface for ease of reworking an assembly. 		ANSI/UL 94 small-scale test data does not pertain to building materials, furnishings and related						
5591S	UL 94 V-1 or V-0	Short Term (Hours-Days) 160-180°C	2) 3M Pad 5591S is available in 0.5 mm -2.0 mm thickness.3) Optional thickness > 2.0 mm are available.	contents. ANSI/UL 94 small- scale test data is intended solely						
5592	UL 94 V-1 or V-0	Long Term (Weeks-Months) 130-140°C	 3M Pad 5592S is Thermal Pad 5592 with a polymeric film on one side to be used as a non-tacky surface for ease of reworking and assembly. Thermal conductivity and thermal impedance are slightly changed with addition of the film, while dielectric strength is improved. 	for determining the flammability of plastic materials used in the components and parts of end- product devices and appliances, where the acceptability of the combination is determined by UL.						
5592S	0231710173	130-140 C	2) 3M Pad 5592S is available in the 0.5 mm-2.0mm thickness. 3M Pad 5592 1.0-2.0 mm thickness 3) Optional thicknesses > 2.0 mm are available.							
5595	III 04W 0	Short Term (Hours-Days) 180-200°C	 3M Pad 5595S is Thermal Pad 5595 with a polymeric film on one side to be used as a non-tacky surface for ease of reworking and assembly. Thermal conductivity and thermal impedance are slightly changed with addition of the film, while dielectric strength is improved. 	,						
5595S	UL 94 V-0	Long Term (Weeks-Months) 150-160°C	2) 3M Pad 5595S is available in the 0.5 mm-2.0 mm thickness. 3M Pad 5595 1.0-2.0 mm thickness 3) Optional thicknesses > 2.0 mm are available.							
3M™ Thermally (Conductive Acrylic	Interface Pads								
5570			3M Pad 5570 has good recovery and a medium tack surface for both sides and uses an acrylic elastomer for applications that require a non-silicone thermal pad.							
5571		Short Term (Hours-Days)	3M Pad 5571 has good recovery and a medium tack surface for both sides and uses an acrylic elastomer for applications that require a non-silicone thermal pad.	ANSI/UL 94 small-scale test data does not pertain to building						
5578H	UL 94 V-0	110-130°C Long Term	3M Pad 5578H has good recovery, a low tack surface and a very low tack surface, and uses an acrylic elastomer for applications that require a non-silicone thermal pad.	materials, furnishings and related contents. ANSI/UL 94 small-scale test data is intended solely for determining the flammability of plastic materials used in the components and parts of end-						
5589H		(Weeks-Months) 90-100°C	3M Pad 5589H has a very low tack surface and a medium tack surface and uses an acrylic elastomer for applications that require a non-silicone thermal pad.							
5590H			3M Pad 5590H has a very low tack surface and a medium tack surface and uses an acrylic elastomer for applications that require a non-silicone thermal pad.	product devices and appliances, where the acceptability of the combination is determined by UL.						
5567H			3M Pad 5567H has low odor, a very low tack surface and a medium tack surface on soft layer and uses an acrylic elastomer for applications that require a non-silicone thermal pad.	·						

^{****} End use application testing will determine final temperature range based on final design and other environmental conditions. Suggested temperature range is based on a UL-746 Test Method or a 3M Test Method.

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3M[™] Thermally Conductive Epoxies

This range of liquid adhesives has less odor and good structural strength adhesion. Dispensing is easy for high output, in-line automated manufacturing and manual application.

Adhesive flows and fills micro-spaces on surfaces. Ultra-thin bond line helps achieve low thermal impedance.

3M™ Thermally Conductive Epoxies Selection Guide

	ı	Descri	ptior	1	Thermal Performance		Dielectric Properties				
Product	Base Material Type	Product Thickness mil(mm)	Filler Type	Packaging	Conductivity (W/m-K 3M-ASTM 05470TM)	Impedance °C-in²/W(°C-cm²/W) 2.0 mil (50µm) bondline thickness	Dielectric Strength (kV/mm)	Volume Resistivity (ohm/cm)	Potential Operating Temperature Range* (°C)	Typical Applications	Notes

3M™T	herm	ally C	ondi	uctiv	re Epox	ies			
TC-2707	Filled Epoxy	Various	Aluminum Metal	2-part Epoxy/3M Duo-Pak	0.72	0.105 (0.67)	2.1	2.4×10 ¹¹	As the 3M™ Thermally Conductive Adhesive TC-2707 uses aluminum metal fillers, under certain end use application conditions the effective resistivity and/ or effective dielectric strength could be significantly lower than noted. If the metal fillers are "trapped" or "pinched" between two surfaces, an electrical bridge path via the aluminum fillers could occur between these surfaces. Epoxy Adhesive TC-2707 is not suggested for applications where a powered electrical circuit is used or where a reliable volume resistivity and/ or dielectric strength is desired. 3M™ Thermally Conductive Epoxy Adhesive TC-2810 uses ceramic filler and is suggested product to test for these types of application performance needs.
TC-2810			Ceramic		1.0-1.4	0.05 (0.32)	3	76 × 10 ¹²	Thermal Conductivity (TC) can vary in an application as the filler is a boron nitride (BN) platelette shape and alignment can change effective TC.

^{*} End use application testing will determine final temperature range based on final design and other environmental conditions. Suggested temperature range is based on a UL-746 Test Method or a 3M Test Method.

3M™ EPX Applicator and Nozzle simultaneously and accurately mixes, meters, and applies adhesive with a squeeze of the trigger

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The 3M™ Thermally Conductive Greases are high performance thermal interface materials for transferring thermal energy from a heat source (e.g. processor chip, graphics chip, High Power LED) to a heat sink. The proprietary blend of inorganic fillers contained in an organic matrix (non-silicone) ensures high thermal conductivity and low thermal resistance. Grease products are available in two versions: Standard viscosity and a lower viscosity version that can be useful in screen printing application methods.

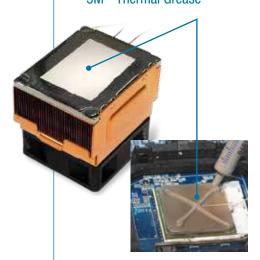
3M™ Thermally Conductive Greases Selection Guide

		Desc	crip	tion	Theri Perforn		Dielec Proper				
Product	Base Material Type	Product Thickness mil(mm)	Filler Type	Steady State Shear Viscosity @ 1.0 Shear/Rate	Conductivity (W/m-K3M-ASTM 05470 TM)	Impedance °C-in²/W (°C-cm²/W)	Dielectric Strength KV/mm (Film version tested)	Volume Resistivity (ohm/cm)	Potential Operating Temperature Range* (°C)	Typical Applications	Notes
3M [™] The	rma	lly Co	ndu	ctive Gre	ases						
TCG-2035/ TCG-2031	Non-Silicone Polymeric Binder	Various	Ceramic	2100/150	4.1	0.0127 (0.81)	4.7	1.36 × 10 ⁹	Short Term (Hours-Days) 125-150°C Long Term (Weeks-Months) 100-125°C	Thermally conductive greases provide a thin thermal interface to optimize thermal heat transfer between hot running devices and heat sinking surfaces. Excellent flow properties for improved interface wet-out.	3M Greases TCG-2031 and TCG-2033 are supplied with a small wt% of a solvent added to lower viscosity. Lower viscosity can allow for reduced thickness during application and may benefit screen printing options. Effective thermal measurements are not significantly different from non-solvent added versions. Shear rate viscosity reduced by 5-10×.

^{*} End use application testing will determine final temperature range based on final design and other environmental conditions. Suggested temperature range is based on a UL-746 Test Method or a 3M Test Method.

3M[™] Thermally Conductive Greases

3M[™] Thermal Grease



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